

Features

- Halogen Free. "Green" Device (Note 1)
- Lead Free Finish/RoHS Compliant(Note 2) ("P" Suffix Designates Compliant. See Ordering Information)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Moisture Sensitivity Level 1
- Low Switching Losses and High Efficiency
- Low Reverse Leakage
- Ultrafast Recovery Time
- Planar Structure Die and Soft Recovery Characteristics

30 Amp FRED Rectifiers 600 Volts

Maximum Ratings @ 25°C (Unless Otherwise Specified)

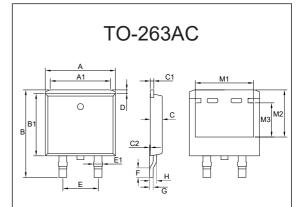
Parameter	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}		
Working Peak Reverse Voltage	V _{RWM}	600	V
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{RMS}	420	V
Average Rectified Forward Current			
Per Diode Per Device	I _{F(AV)}	15 30	А
Non-Repetitive Peak Surge Current @8.3ms Half Sine Wave	I _{FSM}	200	А
Current Squared Time @ 1ms≤t≤8.3ms	l ² t	166	A ² s

Internal Structure

Pin	Description	Simplified Outline	Graphic Symbol
2&4	Cathode		
1&3	Anode	MCC	1 •—
		MURBF3060CT	3 ○ → 2&4

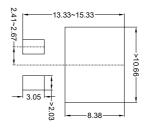
Note:

- 1.Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 2. High temperature solder exemption applied, see EU directive annex 7a.



	DIMENSIONS						
DIM		HES	MM		NOTE		
ווועו	MIN	MAX	MIN	MAX	NOTE		
Α	0.388	0.407	9.85	10.35			
A1	0.323	0.339	8.20	8.60			
В	0.467	0.490	11.85	12.45			
B1	0.346	0.361	8.78	9.18			
С	0.062	0.074	1.57	1.87			
C1	0.014	0.026	0.35	0.65			
C2	0.000	0.008	0.00	0.20			
D	0.015	0.027	0.39	0.69			
Е	0.196	0.204	4.98	5.18			
E1	0.044	0.056	1.12	1.42			
F	0.051	0.059	1.30	1.50			
G	0.014	0.026	0.35	0.65			
Н	0.033	0.049	0.85	1.25			
M1	0.327	0.343	8.30	8.70			
M2	0.264	0.280	6.70	7.10			
М3	0.185	0.201	4.70	5.10			

Suggested Solder Pad Layout(mm)





Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
T_J	Operating Junction Temperature Range		-55		175	ô
T _{stg}	Storage Temperature Range		-55		175	°C
Rth _(J-C)	Thermal Resistance from Junction to Case			2		°C/W

Electrical Characteristics @ 25°C Unless Otherwise Specified

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Forward Voltage	V _F	I _F =15A;T _J =25°C		1.08	1.25	V
		I _F =15A;T _J =125°C		0.91	1.15	V
Reverse Current	I _R	V _R =600V;T _J =25°C			10	uA
		V _R =600V;T _J =125°C			100	uA
Junction Capacitance	CJ	V _R =600V;f=1MHz;T _J =25°C		20		pF

Dynamic Recovery Characteristics @ 25°C Unless Otherwise Specified

Parameter	Symbol	Test Conditions		Min	Тур	Max	Unit
	t _{rr}	I _F =0.5A; I _R =1.0A;I _{RR} =0.25A;T _J =25°C			50	55	
Reverse Recovery Time		I _F =1A,di _F /dt=-50A/us,V _R =30V;T _J =25°C			57		ns
		I _F =15Α di _F /dt=-200Α/ μs V _{RM} =400V	T _J =25°C		92		110
			T _J =125°C		138		
Dook Doorway Cumont	Peak Recovery Current		T _J =25°C		9.24		Α
Peak Recovery Current			T _J =125°C		16.12		A
Reverse Recovery Charge Q _{rr}	0		T _J =25°C		425		nC
	Q rr		T _J =125°C		1115		110



Curve Characteristics

Fig. 1 - Forward Current Derating Curve

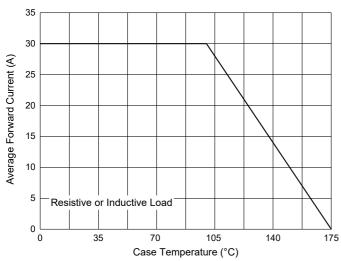


Fig. 3 - Typical Forward Characteristics

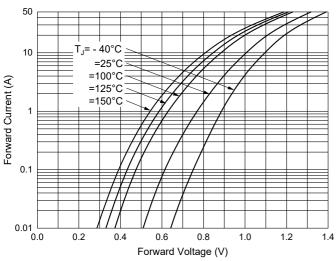


Fig. 5 - Typical Capacitance Characteristics

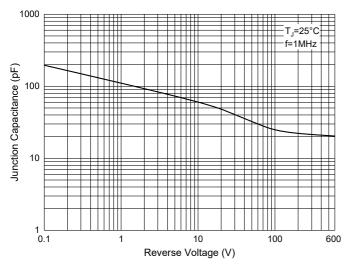


Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current

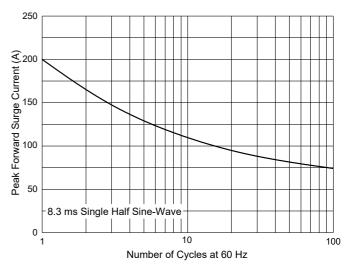


Fig. 4 - Typical Reverse Leakage Characteristics

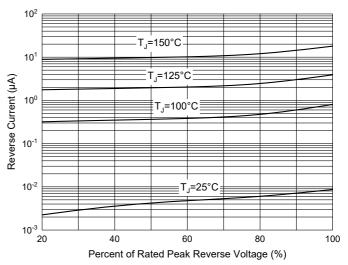
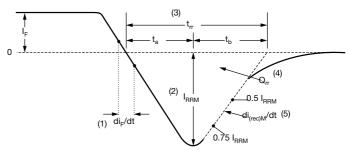


Fig. 6 - Reverse Recovery Waveform and Definitions



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 1500pcs/Reel

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